

Abstract of the Disclosure

An electrostatic chuck having a bonded structure comprising a ceramic electrostatic chuck member, a metal member and a bonding layer; the bonding layer having at least a first most outer bonding layer being joined to the ceramic electrostatic chuck member, a second most outer bonding layer being joined to the metal member, and a polyimide layer as an intermediate layer disposed between the first and second most outer bonding layers, and each of the most outer bonding layers being made of a silicone layer or an acrylic layer, and a method for manufacturing the same are provided: the bonding layer being excellent in airtightness, bonding strength, and corrosion resistance, free from bleeding of a bonding material even under high pressures at time of joining, and the junction body being good in heat conductivity, and having a good flatness of its adsorption surface, with a small deformation due to temperature change.

200110-0059001